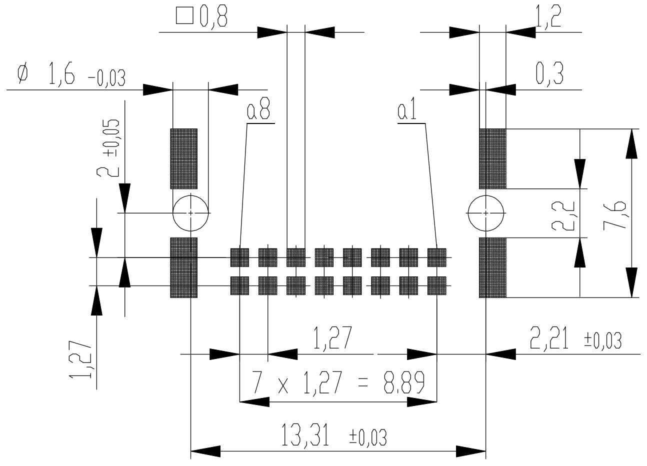
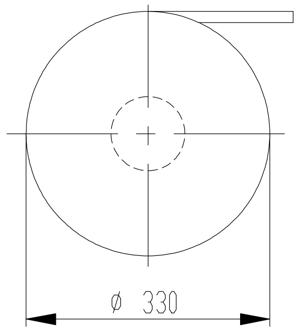
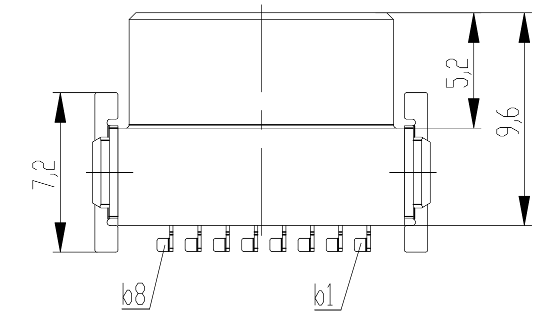
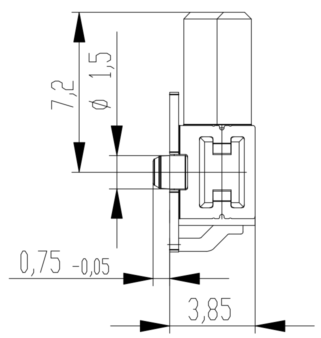
Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT

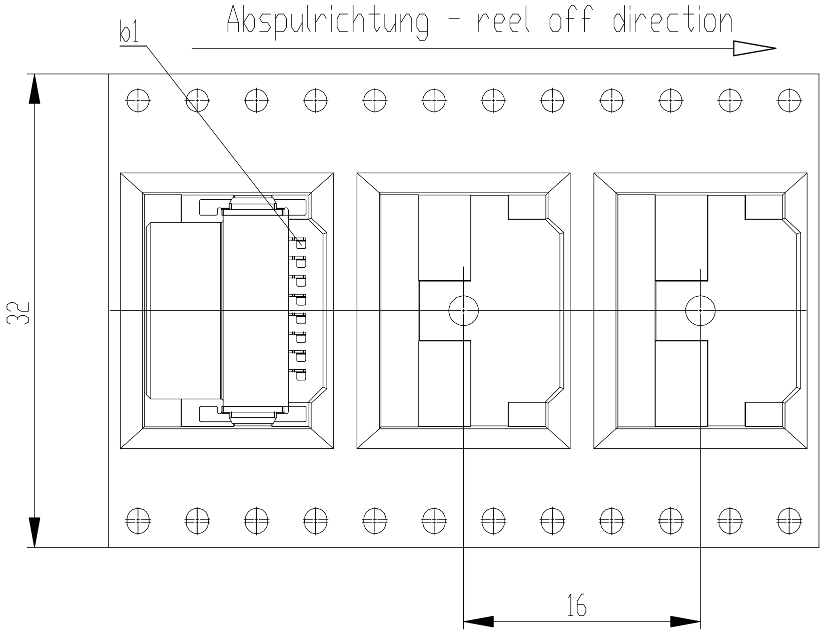


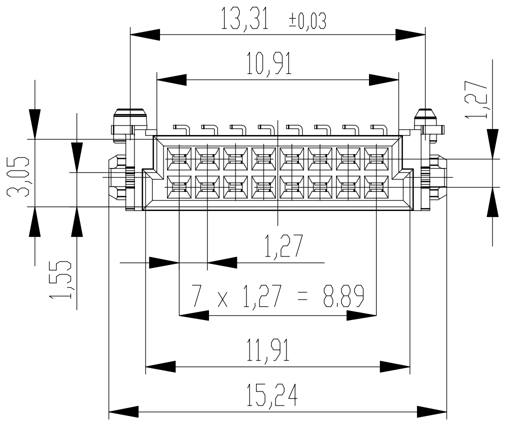
Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
tape on reel packaging according to DIN IEC 60286-3
Verpackungseinheit: 560 Stück
packaging unit: 560 pcs









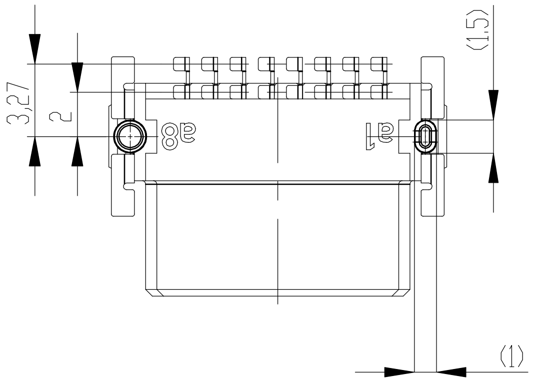


Anforderungsstufe 1
performance level 1

Kontaktbereich vergoldet
mating area gold plating

Anschlussbereich verzinnt 4-6 µm
terminal area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
coplanarity area of termination ≤ 0,1 mm



Weitergabe sowie Vervielfältigung dieses Dokuments, Verwertung und Mitteilung seines Inhalts sind verboten, sowie nicht ausdrücklich gestattet. Zuwiderhandlungen verpflichten zu Schadenersatz.
Alle Rechte für den Fall der Patent-, Gebrauchsmuster- oder Geschmacksmustereintragung vorbehalten.
The reproduction, distribution and utilization of this document as well as the communication of its contents to others without express authorization is prohibited. Offenders will be held liable for the payment of damages. All rights reserved in the event of the grant of a patent, utility model or design.

Die deutsche Version dieser Zeichnung dient nur zur Erleichterung der Handhabung. Bei Abweichungen von dem englischen Original gilt das englische Original.
The german version of this drawing has been offered for convenience only and may deviate from the english original.
In case of any deviation the English version shall prevail.

BA7-03 - Standard Bauhöhe
type7-03 - Standard Assembly Height

Dimension no.

Tolerances
Dim. for Information
ISO 8015

All Dimensions in mm

Scale 5:1
Material

Customer drawing:

THIS DRAWING IS A CONTROLLED DOCUMENT.

Subject to modification without prior notice.
Drawing will not be updated.

ERNI-Federl. SMC-Q 16-SMD-BA7-03
Female SMC-Q 16-SMD-type7-03

TE Connectivity

C- 354078-E

I
A3

Index	Date
c	07.02.2020

Class SMCQ